

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended) ~~A chip carrier including a metal-coated portion formed on a front surface of a substrate and to be mounted a device, and a rear surface of the substrate being coated with a metal, wherein~~

~~_____ a metal-coated portion is formed on a side surface of the substrate, and wherein~~

~~_____ the metal-coated portion on the front surface of substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate.~~ A chip carrier including a dielectric or semiconductor substrate, one surface of which includes a metal-coated portion and an opposite surface of which includes a metal-coated mount portion to at least one high-frequency device, wherein

said metal-coated portion of said one surface is connected with said metal-coated portion of said opposite surface through a metal-coated portion formed on a side surface of said substrate.

Claim 2 (Currently Amended) The chip carrier according to claim 1, wherein the metal-coated portion on the ~~front~~one surface of the substrate is connected with the metal-coated portion on the ~~rear~~opposite surface by a metallic via-hole formed on passing through the substrate.

Claim 3 (Currently Amended) ~~A chip carrier including a metal coated portion formed on a front surface of a substrate and mounted an optical semiconductor device, and a rear surface of the substrate being coated with a metal, wherein~~
~~— a metal coated portion is formed on a side surface of the substrate, and~~
wherein

~~— the metal coated portion on the front surface of substrate is connected with the metal coated portion on the rear surface by the metal coated portion formed on the side surface of the substrate.~~
A chip carrier including a dielectric or semiconductor substrate, one surface of which includes a metal-coated portion and an opposite surface of which includes a metal-coated portion, a high frequency transmission line is arranged on said one surface of the substrate and a semiconductor device is mounted on said metal-coated portion formed on said one surface of the substrate, wherein

said metal-coated portion of said one surface is connected with said metal-coated portion of said opposite surface through a metal-coated portion formed on a side surface of said substrate.

Claim 4 (Currently Amended) The chip carrier according to claim 3, wherein the metal-coated portion on the ~~front~~one surface of the substrate is connected with the metal-coated portion on the rear~~opposite~~opposite surface by a metallic via-hole formed on passing through the substrate.

Claim 5 (Original) The chip carrier according to claim 3, wherein the metal-coated portion formed on the side surface of the substrate is formed on the side surface closest to a position at which the optical semiconductor device is mounted.

Claim 6 (Original) The chip carrier according to claim 5, wherein an area of the metal-coated portion formed on the side surface of the substrate is equal to or greater than 1/3 of the side surface.

Claims 7-16 (Cancelled)

Claim 17 (New) A chip carrier including a dielectric or semiconductor substrate having a metal-coated portion formed on a front surface of the substrate to mount a device, and metal-coated portion formed on a rear surface of the substrate, wherein

a metal-coated portion is formed on a side surface of the substrate, and wherein

the metal-coated portion on the front surface of substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate.

Claim 18 (New) The chip carrier according to claim 17, wherein the metal-coated portion on the front surface of the substrate is connected with the metal-coated portion on the rear surface by a metallic via-hole formed through the substrate.

Claim 19 (New) A chip carrier including a dielectric or semiconductor substrate having a metal-coated portion formed on a front surface of a substrate to

mount an optical semiconductor device, and a metal-coated portion on a rear surface of the substrate, wherein

a metal-coated portion is formed on a side surface of the substrate, and wherein

the metal-coated portion on the front surface of substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate.

Claim 20 (New) The chip carrier according to claim 19, wherein the metal-coated portion on the front surface of the substrate is connected with the metal-coated portion on the rear surface by a metallic via-hole formed through the substrate.

Claim 21 (New) The chip carrier according to claim 19, wherein the metal-coated portion formed on the side surface of the substrate is formed on the side surface closest to a position at which the optical semiconductor device is mounted.

Claim 22 (New) The chip carrier according to claim 21, wherein an area of the metal-coated portion formed on the side surface of the substrate is equal to or greater than 1/3 of the side surface.

Claim 23 (New) A chip carrier including a dielectric or semiconductor substrate having a metal-coated portion formed on a front surface of the substrate to mount a device, and metal-coated portion formed on a rear surface of the substrate, and

an inductance reducer structure in a form of a metal-coated portion formed on a side surface of the substrate, and wherein

the metal-coated portion on the front surface of substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate.

Claim 24 (New) The chip carrier according to claim 23, including a secondary inductance reducer structure in a form of a metallic via-hole formed through the substrate wherein the metal-coated portion on the front surface of the substrate is connected with the metal-coated portion on the rear surface by the metallic via-hole formed through the substrate.

Claim 25 (New) A chip carrier including a dielectric or semiconductor substrate having a metal-coated portion formed on a front surface of a substrate to mount an optical semiconductor device, and a metal-coated portion on a rear surface of the substrate, and

an inductance reducer structure in a form of a metal-coated portion formed on a side surface of the substrate, and wherein

the metal-coated portion on the front surface of substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate.

Claim 26 (New) The chip carrier according to claim 25, including a secondary inductance reducer structure in a form of a metallic via-hole formed through the substrate wherein the metal-coated portion on the front surface of the substrate is

connected with the metal-coated portion on the rear surface by the metallic via-hole formed through the substrate.

Claim 27 (New) The chip carrier according to claim 25, wherein the metal-coated portion formed on the side surface of the substrate is formed on the side surface closest to a position at which the optical semiconductor device is mounted.

Claim 28 (New) The chip carrier according to claim 27, wherein an area of the metal-coated portion formed on the side surface of the substrate is equal to or greater than 1/3 of the side surface.

Claim 29 (New) An optical module comprising:

a chip carrier including a dielectric or semiconductor substrate having a metal-coated portion formed on a front surface of a substrate to mount an optical semiconductor device, and a metal-coated portion on a rear surface of the substrate wherein a metal-coated portion is formed on a side surface of the substrate, and wherein the metal-coated portion on the front surface of the substrate is connected with the metal-coated portion on the rear surface by the metal-coated portion formed on the side surface of the substrate; and

the optical semiconductor device mounted to the metal-coated portion on the front surface of the substrate.

Claim 30 (New) The optical module according to claim 29, wherein the metal-coated portion on the front surface of the substrate is connected with the metal-

coated portion on the rear surface by a metallic via-hole formed through the substrate.

Claim 31 (New) The optical module according to claim 29, wherein the metal-coated portion formed on the side surface of the substrate is formed on the side surface closest to a position at which the optical semiconductor device is mounted.

Claim 32 (New) The optical module according to claim 31, wherein an area of the metal-coated portion formed on the side surface of the substrate is equal to or greater than 1/3 of the side surface.